

Production sockets for JEDEC Type "C" LCC chips.

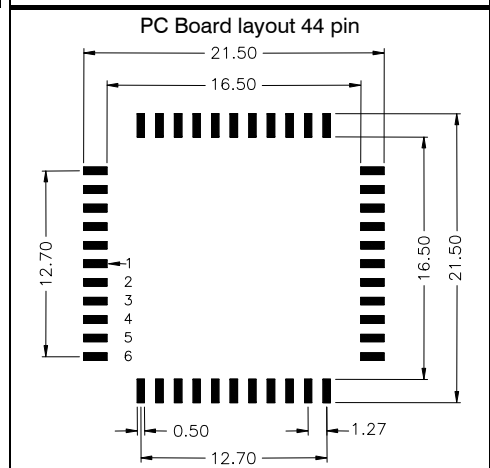
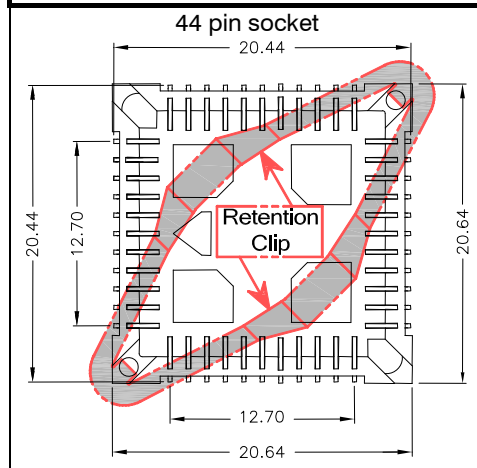
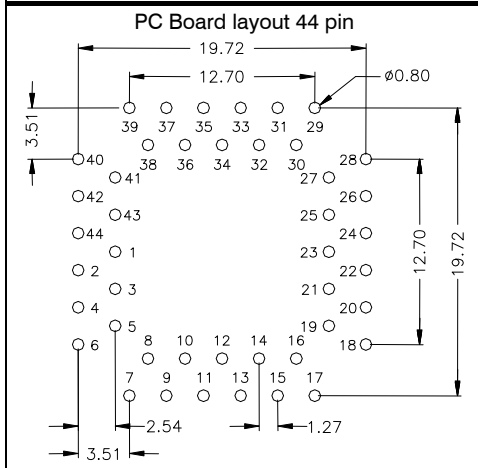
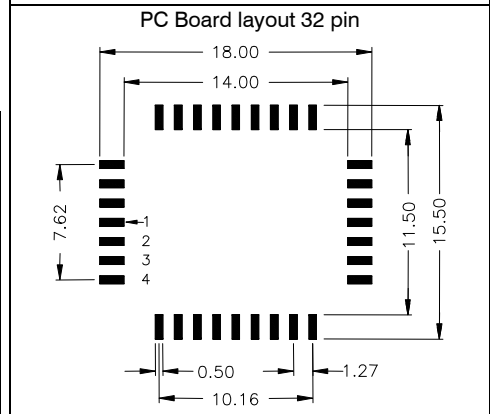
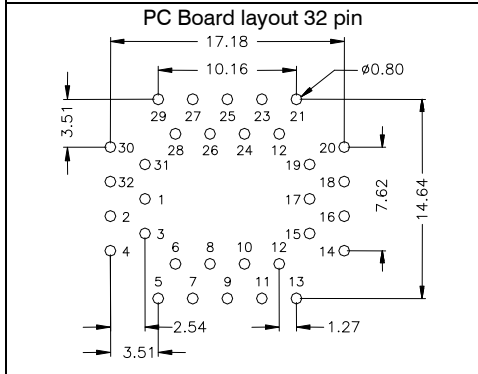
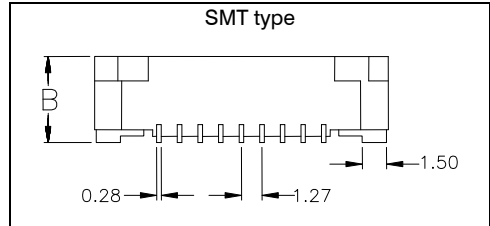
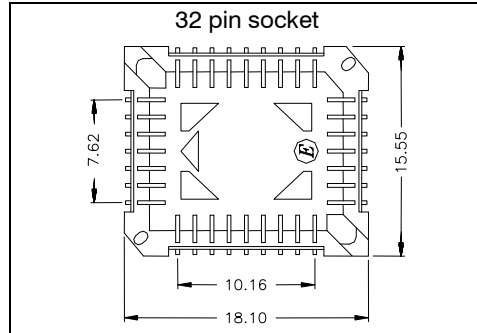
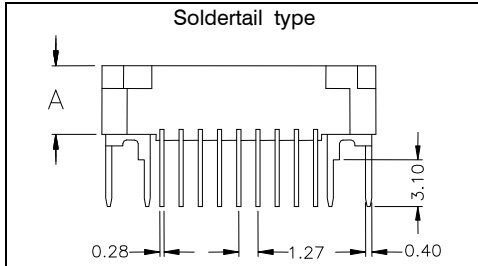
Socket design for automatic assembly and vacuum pick and place machines, available in soldertail and SMT version.

In order to ensure compatibility with newer generation 44-pin LCC chip packages we have replaced the previous H200 contact style by new style H403. The previous generation 44-pin chip packages are also adapted to this new contact style.

The SMT terminals extend beyond the side of the socket body, which permits direct access of the infrared heat to the terminal, thus preventing an undesired heat exposure of the insulator.

Optional retention clips are available, which can be mounted and demounted without any tools.

Chips can be easily removed with the Universal extraction tool PUL-200.



Pin	Soldertail Type Ordering Code	DIM "A"
32	LCC-032-H210-55	5,20/.244
44	LCC-044-H210-55	6,80/.268

Retention Clip Styles - Ordering Code	
32-pin	= HCL-032/S (square)
32-pin	= HCL-032 (diagonal)
44-pin	= HCL-044

Pin	SMT Type Ordering Code	DIM "B"
32	LCC-032-H200-55	5,40/.213
44	LCC-044-H403-55 previous OC: LCC-044-H200-55	6,00/.236

Specifications

Mechanical data

Contact material (RoHS compliant)	BeCu
Plating	Au over Ni over Cu (Sn on request)
Insulator (RoHS compliant)	high temp plastic UL 94 V-0
Operating temperature	-55°C to +125°C
Processing temperature	250°C +0/-5°C for 20-40 Sec.

Electrical data

Insulation resistance at 500V DC	1000 MΩ min.
Breakdown voltage at 60 Hz	700V AC for one min
Contact resistance at 10 mA	30 mΩ max.
Capacitance	1pF max.
Current rating	1 A max., 100V
Pitch	1,27 mm (.050")